

AMENDMENTS TO THE CLAIMS:

This listing of claims will replace all prior versions, and listings, of claims in the application:

LISTING OF CLAIMS:

Claims 1-28 (Cancelled)

29. (Currently Amended) A variable voltage protection component for placement between a ground plane and an electronic circuit comprising:

a layer of variable voltage material comprising a binder containing conductive particles and/or semiconductive particles; and

a layer of neat dielectric polymer or glass distinct from and overlying the layer of variable voltage material and in contact with one surface of the layer of variable voltage material, wherein the layer of neat dielectric polymer or glass does not contain conductive or semiconductive particles, and

wherein the neat dielectric polymer or glass layer is present in a thickness of less than about 1.6 mils, and wherein the layer of variable voltage material and the layer of neat dielectric polymer or glass provide an electrical path through which current from an over voltage event passes to the ground plane.

30. (Previously Presented) A component according to Claim 29 wherein the neat dielectric polymer or glass layer is less than about 0.8 mil in thickness.

31. (Previously Presented) A component according to Claim 29 wherein the neat dielectric polymer or glass layer is less than about 0.5 mil in thickness.

32. (Previously Presented) A component according to Claim 29 wherein the neat dielectric polymer or glass layer is less than about 0.2 mil in thickness.

33. (Previously Presented) A variable voltage protection component for placement between a ground plane and an electronic circuit comprising:

a first layer of variable voltage protection material having a composition comprising a binder having dispersed therein at least about 20% by volume conductive and/or semiconductive particles;

a second layer of variable voltage protection material in contact with the first layer and having a composition which is different from the composition of the first layer and which comprises a binder having dispersed therein at least 40% by volume conductive and/or semiconductive particles; and

a third layer of variable voltage protection material in contact with said second layer and having a composition which is different from the composition of the second layer and which comprises a binder having dispersed therein at least 20% by volume conductive and/or semiconductive particles.

34. (Previously Presented) A component according to Claim 33 wherein at least one of the layers of variable voltage protection material comprises conductive particles and semiconductive particles.

35. (Previously Presented) A component according to Claim 33 wherein the volume percent in the three layers comprise at least about 30%, at least about 40% and at least about 30% respectively.

36. (Previously Presented) A component according to Claim 34 wherein the volume percent in the three layers comprise at least about 30%, at least about 40% and at least about 30%, respectively.

37. (Previously Presented) The component according to Claim 33 wherein the volume percent in the three layers comprise at least about 30%, at least about 60% and at least about 30%, respectively.

38. (Previously Presented) A component according to Claim 34 wherein the volume percent in the three layers comprise at least about 30%, at least about 60% and at least about 30%, respectively.

39. (Previously Presented) A component according to Claim 33 comprising a layer of neat dielectric polymer or glass in contact with at least one of said first, second and third layers wherein the neat dielectric polymer or glass layer is present in a thickness of less than about 1.6 mils.

40. (Previously Presented) A component according to Claim 34 comprising a layer of neat dielectric polymer or glass in contact with at least one of said first, second and third layers wherein the neat dielectric polymer or glass layer is present in a thickness of less than about 1.6 mils.

41. (Previously Presented) A component according to Claim 39 comprising a layer of neat dielectric polymer or glass in contact with at least one of said first, second and third layers.

42. (Previously Presented) A component according to Claim 40 comprising a layer of neat dielectric polymer or glass in contact with at least one of said first, second and third layers.

43. (Currently Amended) A variable voltage protection component for placement between a ground plane and an electronic circuit having an electrical conductor, the component comprising:

a first layer of variable voltage protection material which is in electrical contact with an electrical conductor in said electronic circuit and having composition which ~~which~~ comprises a binder having dispersed therein at least about 20% by volume conductive and/or semiconductive particles; and

a second layer of variable voltage protection material in electrical contact with the first layer and having a composition which is different from the composition of the first

layer and which comprises a binder having dispersed therein at least 40% by volume conductive and/or semiconductive particles.

44. (Previously Presented) A variable voltage protection component according to Claim 43 further comprising a third layer of variable voltage protection material in electrical contact with said second layer and having a composition which is different from the composition of the second layer and which comprises a binder having dispersed therein conductive and/or semiconductive particles at 20% by volume.